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Morad et al.

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(54) **SOLAR PANEL**

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(**) Term: **15 Years**

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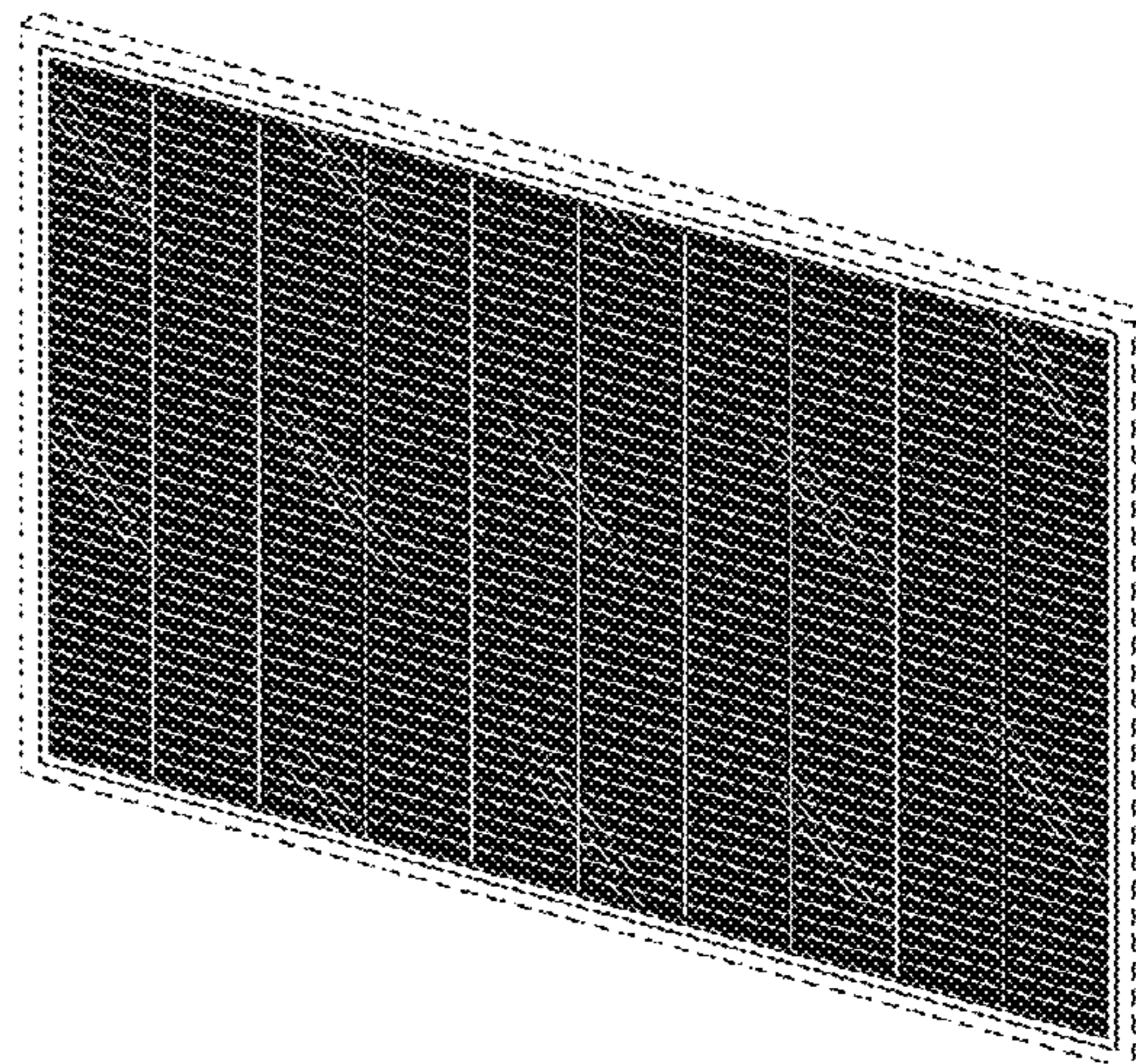
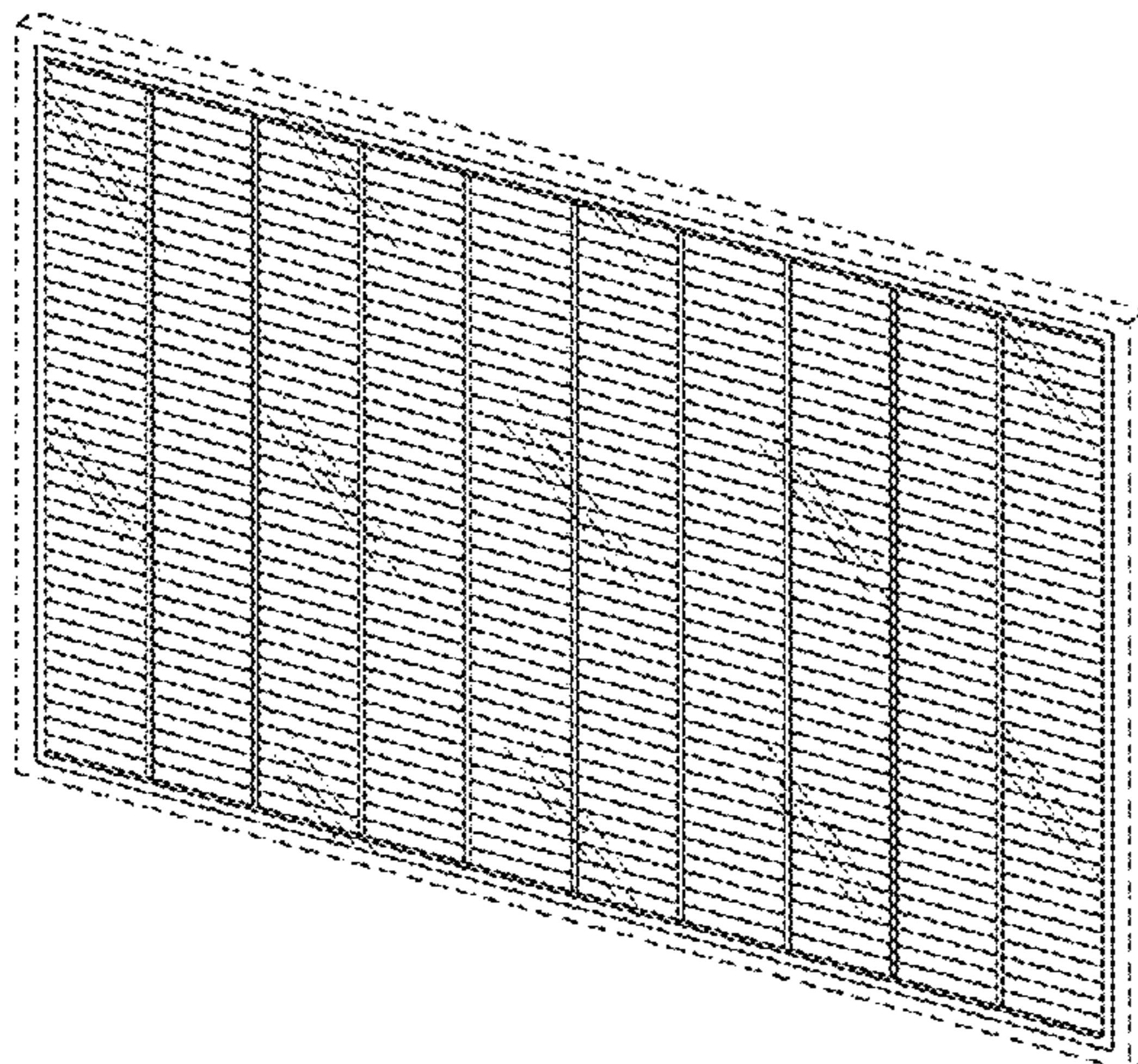
abandoned, and a continuation-in-part of application No. 14/560,577, filed on Dec. 4, 2014, now Pat. No. 9,876,132, and a continuation-in-part of application No. 14/552,761, filed on Nov. 25, 2014, now abandoned, and a continuation-in-part of application No. 14/550,676, filed on Nov. 21, 2014, now abandoned, and a continuation-in-part of application No. 29/509,588, filed on Nov. 19, 2014, now Pat. No. Des. 767,484, and a continuation-in-part of application No. 14/548,081, filed on Nov. 19, 2014, now abandoned, and a continuation-in-part of application No. 29/509,586, filed on Nov. 19, 2014, now Pat. No. Des. 750,556, and a continuation-in-part of application No. 14/543,580, filed on Nov. 17, 2014, now Pat. No. 9,882,077, and a continuation-in-part of application No. 14/539,546, filed on Nov. 12, 2014, now abandoned, and a continuation-in-part of application No. 14/536,486, filed on Nov. 7, 2014, now abandoned, and a continuation-in-part of application No. 29/508,323, filed on Nov. 5, 2014, now abandoned, and a continuation-in-part of application No. 14/532,293, filed on Nov. 4, 2014, now abandoned, and a continuation-in-part of application No. 14/530,405, filed on Oct. 31, 2014, now Pat. No. 9,780,253, and a continuation-in-part of application No. 29/506,755, filed on Oct. 20, 2014, now abandoned, and a continuation-in-part of application No. 29/506,415, filed on Oct. 15, 2014, now abandoned.

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USPC **D13/102**

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See application file for complete search history.



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(57) **CLAIM**

The ornamental design for a solar panel, as shown and described.

DESCRIPTION

FIG. 1 is a front, top, and right side perspective view of a first embodiment of a solar panel;

FIG. 2 is a front elevational view thereof, the rear elevational view forms no part of the claimed design;

FIG. 3 is a top plan view thereof, the bottom plan view being a mirror image of the top plan view shown;

FIG. 4 is a left side elevational view thereof, the right side elevational view being a mirror image of the left side elevational view shown;

FIG. 5 is a detail view along line 5-5 in FIG. 2 of the overlapping cells thereof;

FIG. 6 is a front, top, and right side perspective view of a second embodiment of a solar panel;

FIG. 7 is a front elevational view thereof, the rear elevational view forms no part of the claimed design;

FIG. 8 is a top plan view thereof, the bottom plan view being a mirror image of the top plan view shown;

FIG. 9 is a left side elevational view thereof, the right side elevational view being a mirror image of the left side elevational view shown;

FIG. 10 is a detail view along line 10-10 in FIG. 7 of the overlapping cells thereof;

FIG. 11 is a front, top, and right side perspective view of a third embodiment of a solar panel;

FIG. 12 is a front elevational view thereof, the rear elevational view forms no part of the claimed design;

FIG. 13 is a top plan view thereof, the bottom plan view being a mirror image of the top plan view shown;

FIG. 14 is a left side elevational view thereof, the right side elevational view being a mirror image of the left side elevational view shown; and,

FIG. 15 is a detail view along line 15-15 in FIG. 12 of the overlapping cells thereof.

The broken lines in the drawings illustrate subject matter that forms no part of the claimed design.

1 Claim, 9 Drawing Sheets

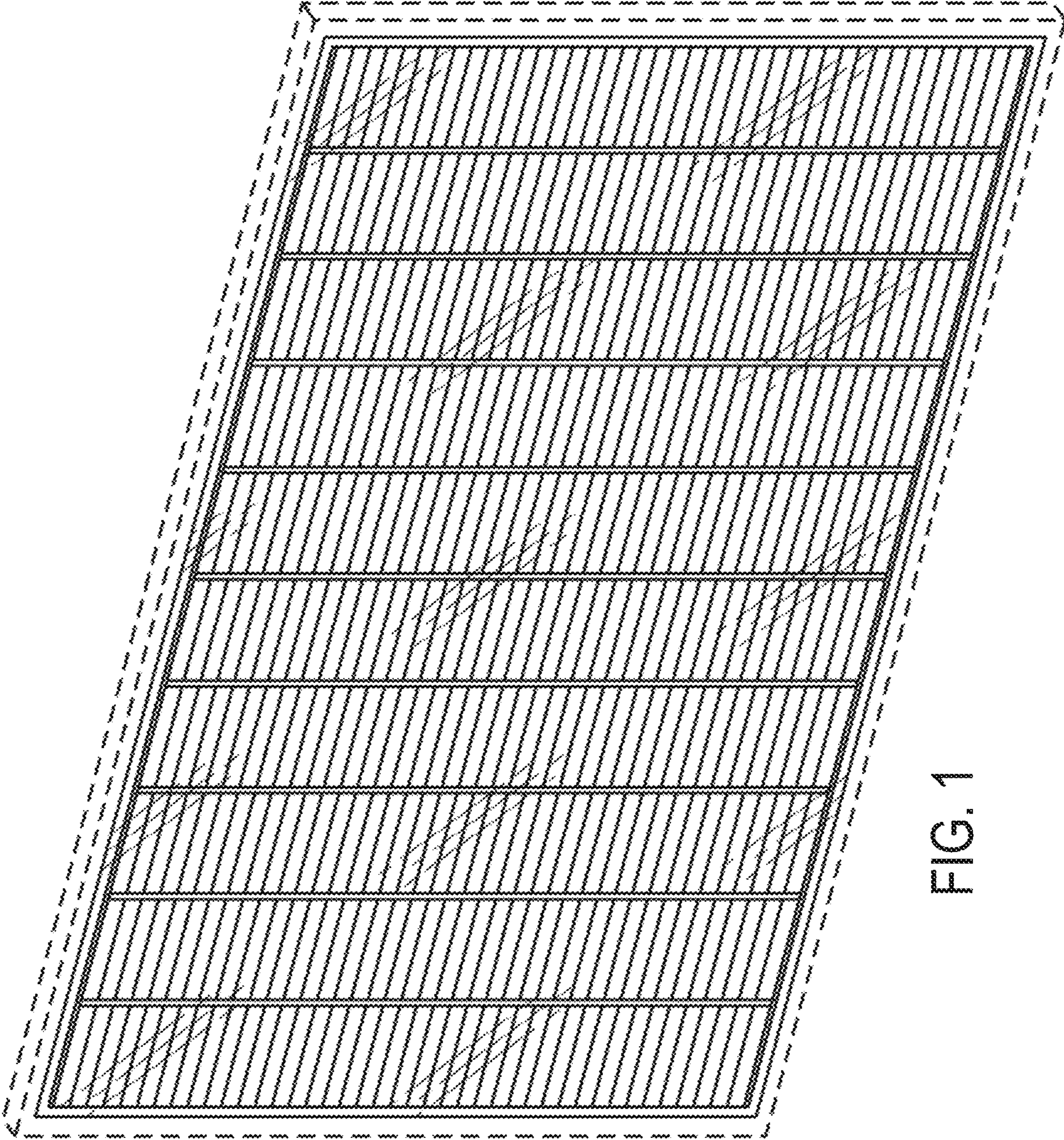


FIG. 1

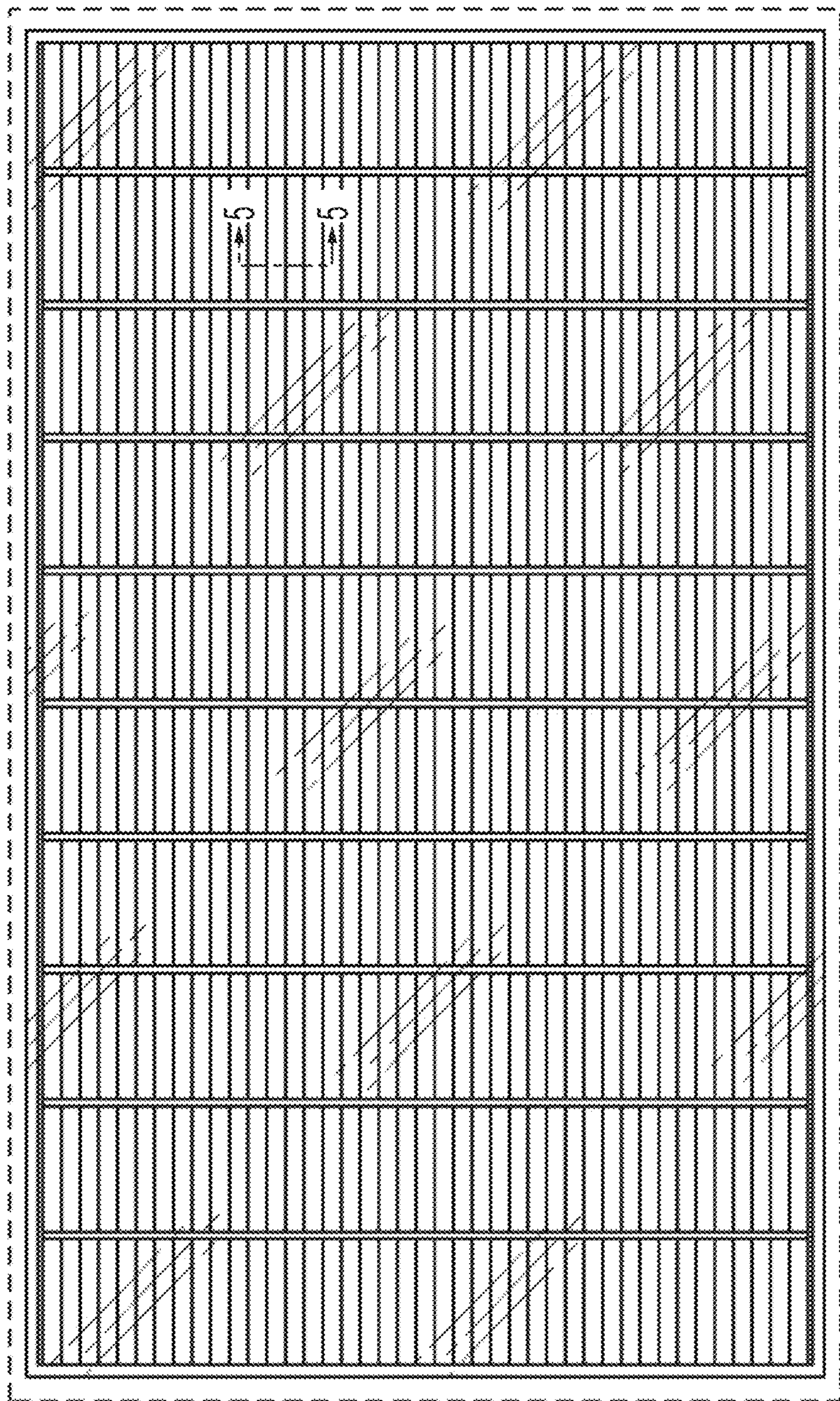


FIG. 2



FIG. 3



FIG. 4



FIG. 5

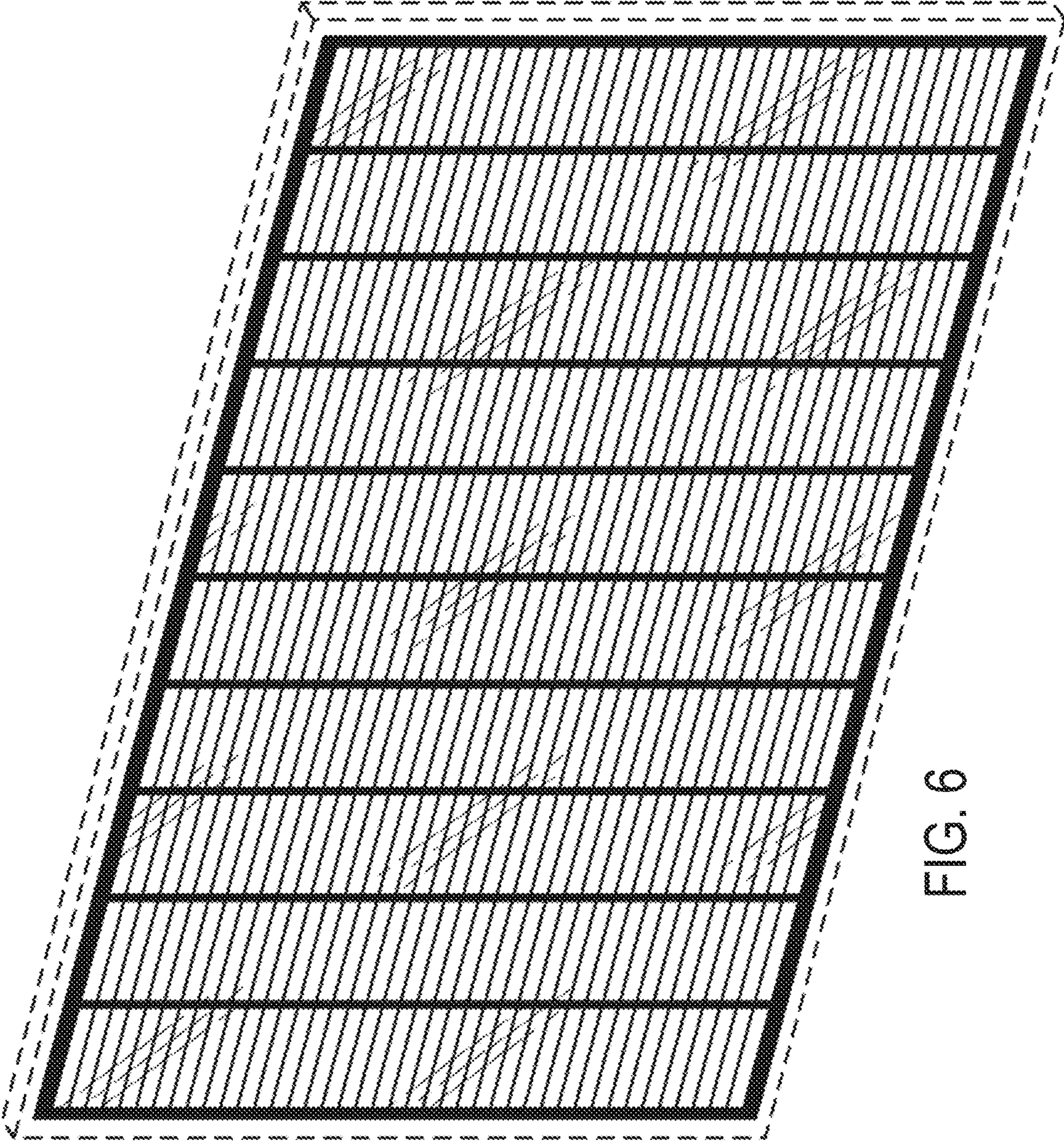


FIG. 6

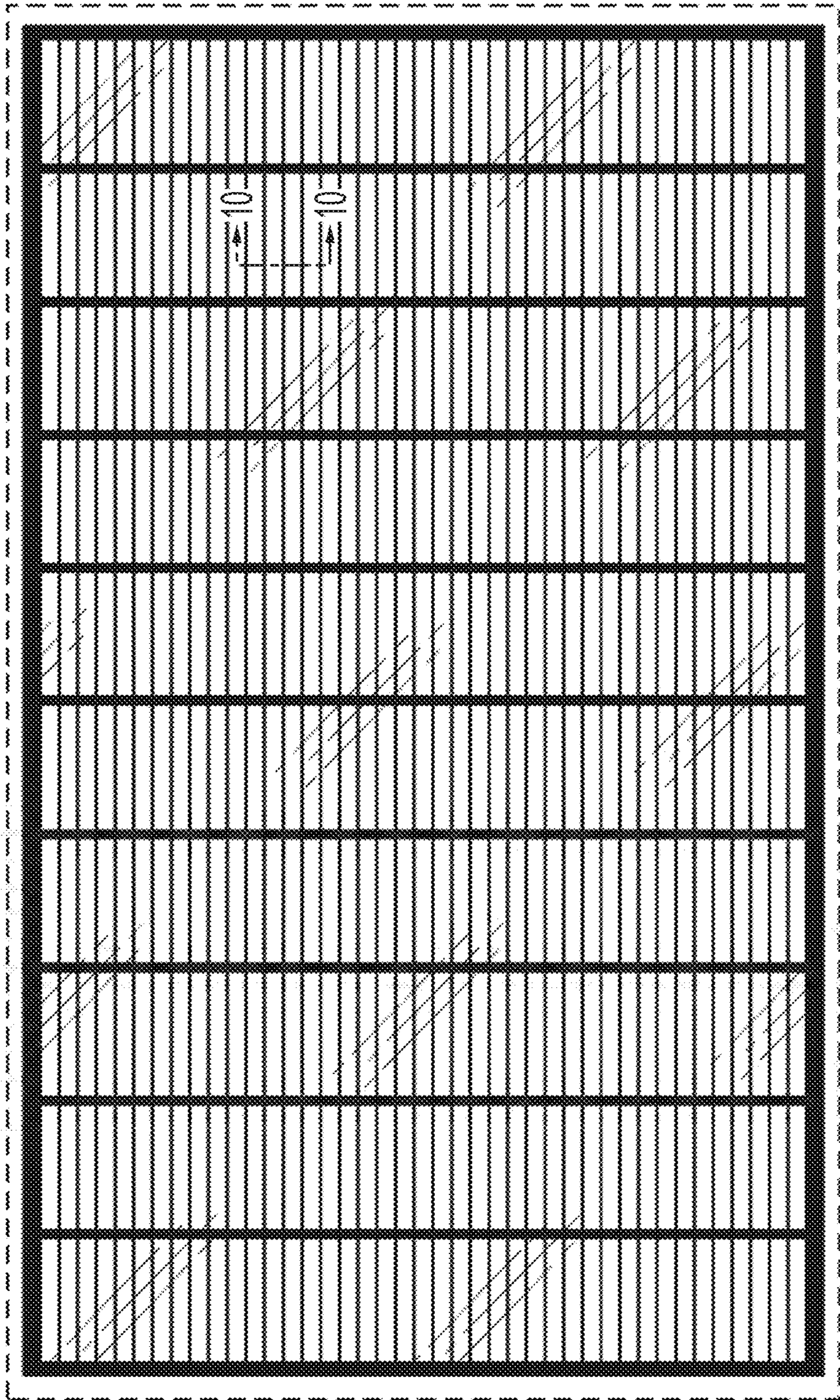


FIG. 7



FIG. 8



FIG. 9



FIG.10

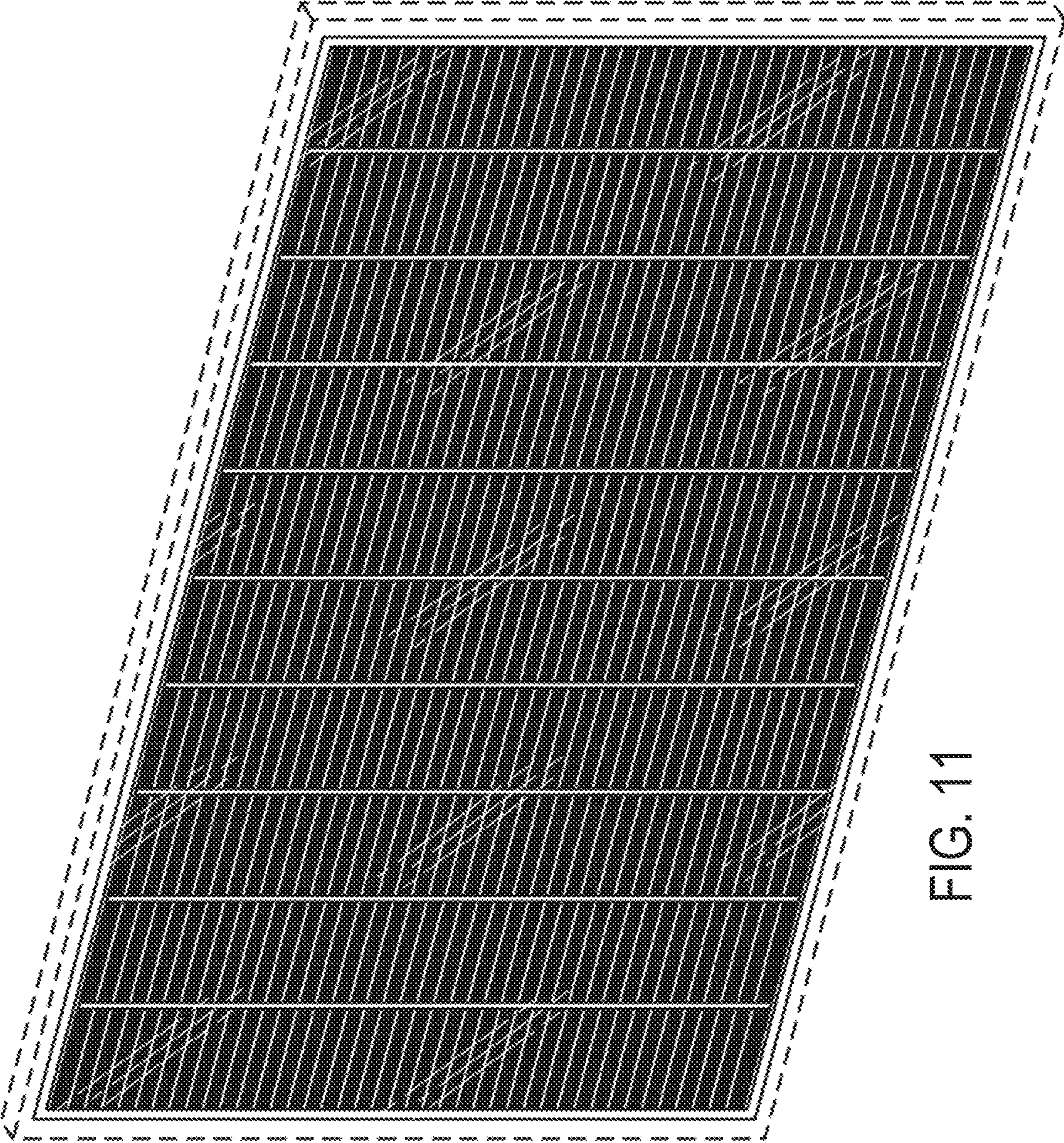


FIG. 11

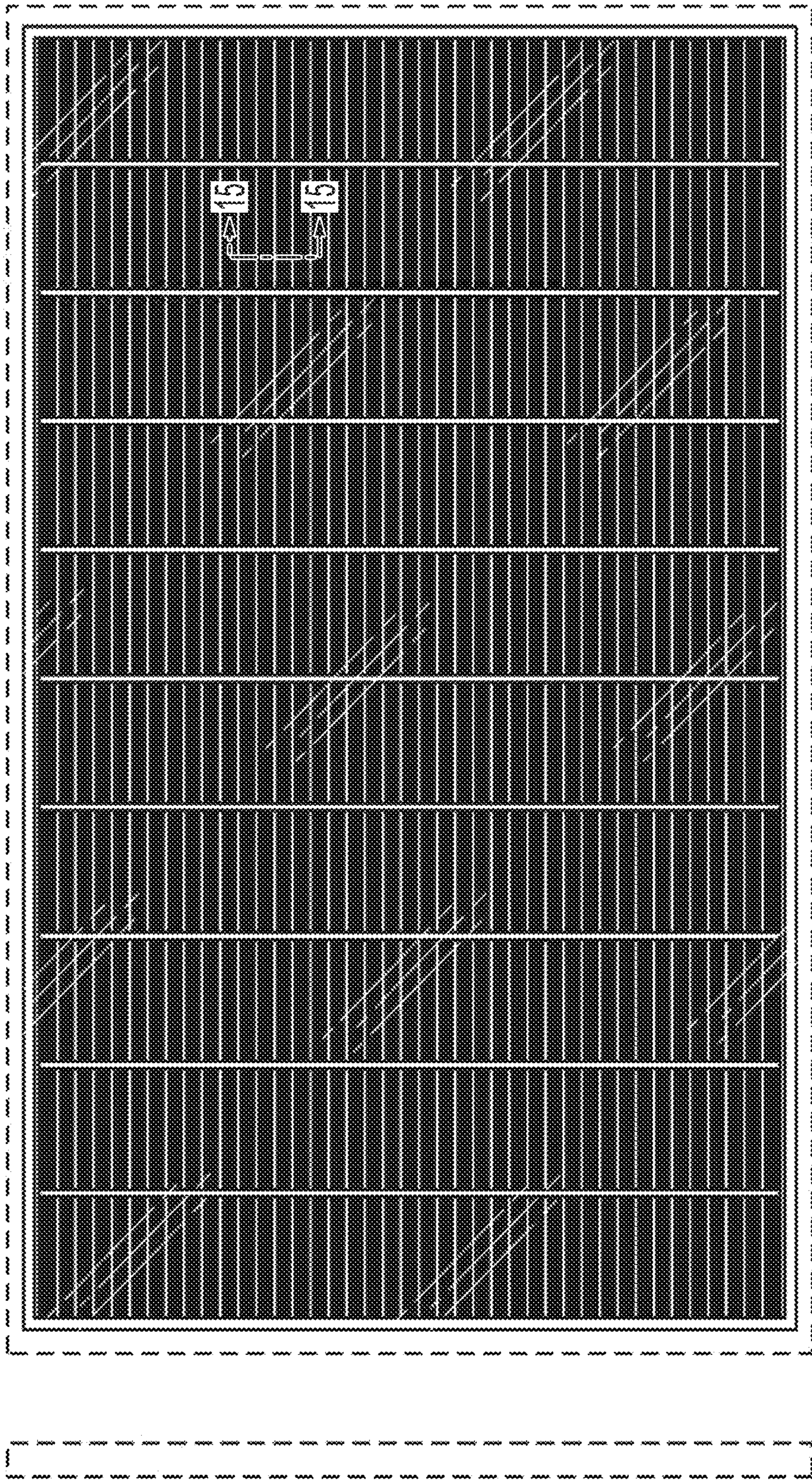


FIG. 12



FIG. 13



FIG. 15